轮毂型电镀超薄切割砂轮
Electroplated bond blades with hub

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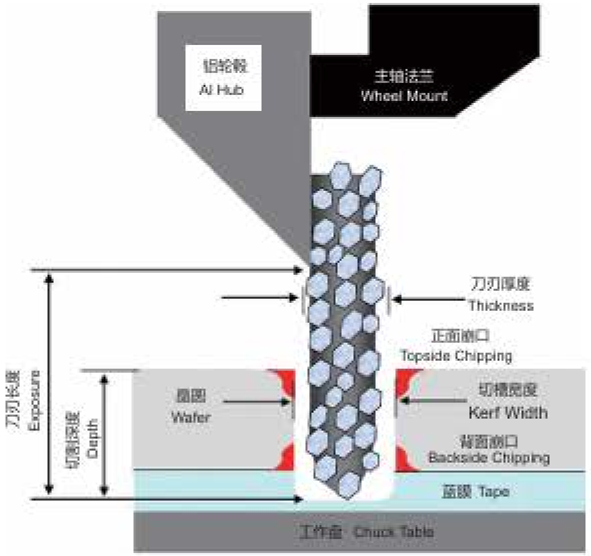
轮毂型电镀超薄切割砂轮用于半导体集成电路及分立器件制造过程中的开槽、切割、划片，主要切割材料有硅片、砷化镓、玻璃、陶瓷、石英、半导体复合材料等。该产品精度高、寿命长，性能达到国外同类产品水平。

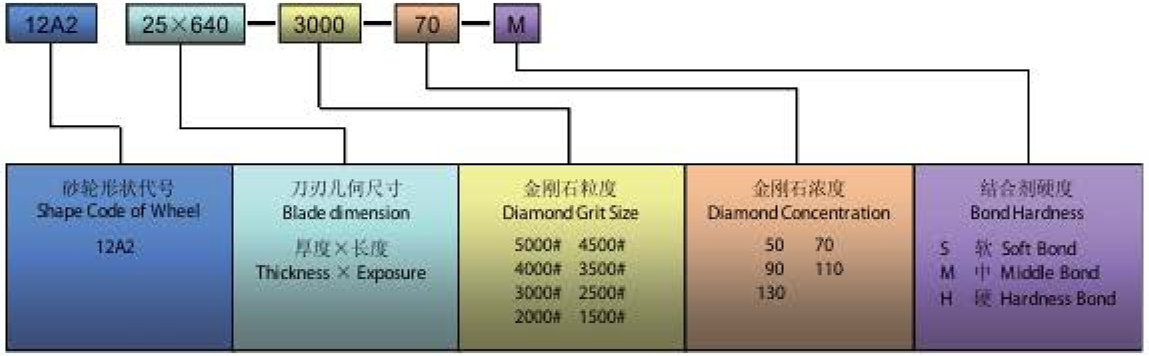
Electroplated bond blades with hub are used to groove, cut, and dice silicon, GaAs, glass, ceramic, quartz and compound semiconductor material wafer in integrated chips and discrete devices production. This product has high precision and long life span. Its performance has achieved abroad advanced level.



- 产品规格 Specification

	刃长基本尺寸 Exposure(μm)	380	510	640	760	890	1020	1150	1270	金刚石粒度 Grit Size	金刚石浓度 Diamond Concen.	结合剂硬度 Bond Hardness
厚度基本尺寸 Thickness(μm)	实际尺寸范围 Tolerance Range(μm)	380~510	510~640	640~760	760~890	890~1020	1020~1150	1150~1270	1270~1400			
20	18~20	20×380	20×510							5000 4500 4000 3500 3000 2500 2000 1500	50 70 90 110 130	S M H
25	21~25	25×380	25×510	25×640								
30	26~30	30×380	30×510	30×640	30×760	30×890						
35	31~35	35×380	35×510	35×640	35×760	35×890	35×1020					
40	36~40	40×380	40×510	40×640	40×760	40×890	40×1020	40×1150				
50	41~50	50×380	50×510	50×640	50×760	50×890	50×1020	50×1150	50×1270			
60	51~60		60×510	60×640	60×760	60×890	60×1020	60×1150	60×1270			
70	61~70			70×640	70×760	70×890	70×1020	70×1150	70×1270			
80	71~80					80×890	80×1020	80×1150	80×1270			
90	81~90						90×1020	90×1150	90×1270			

- 规格示例 Example part number



砂轮形状代号
Shape Code of Wheel
12A2

刀刃几何尺寸
Blade dimension
厚度×长度
Thickness × Exposure

金刚石粒度
Diamond Grit Size
5000# 4500#
4000# 3500#
3000# 2500#
2000# 1500#

金刚石浓度
Diamond Concentration
50 70
90 110
130

结合剂硬度
Bond Hardness
S 软 Soft Bond
M 中 Middle Bond
H 硬 Hardness Bond